Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	2	"6202298".pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/23 07:25
L8	54	("2734154" | "4034468" | "4034469" | "4254431" | "4299715" | "4323914" | "4398975" | "4435611" | "4466483" | "4473113" | "4607277" | "4806111" | "4915167" | "4966142" | "5011787" | "5031308" | "5037312" | "5056706" | "5071787" | "5074947" | "5086558" | "5097387" | "5131582" | "5148141" | "5148265" | "5148266" | "5164566" | "5170930" | "5196371" | "5198189" | "5223747" | "5237130" | "5323294" | "5325265" | "5328087" | "5445308" | "5455390" | "5459352" | "5542602" | "5553769" | "5557501" | "5561590" | "5572404" | "5651179" | "5658831" | "5688721" | "5720100" | "5808874" | "5819406" | "5920125" | "5975408" | "6000127"). PN. OR ("6202298"). URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/09/23 07:34
L12	1	8 and (permanent or remov$3) and (solder with mask)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/23 07:34

L13	9	8 and mask	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/23 07:36
L14	1	"6437240".pn. and mask	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/23 07:37
L15	1	"6846700".pn. and mask	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/23 07:39
L19	1	electronic near50 assembly and (forming or formed or form) near50 (removable or remove or removed or removing or permanent) near50 solder near50 mask near50 conductive near50 contact near50 pad	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/23 08:04
L20	18	("3096466" | "3335327" | "3393449" | "3644792"). PN. OR ("3771101"). URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/09/23 08:02

L23	13	(forming or formed or form) near50 (removable or remove or removed or removing or permanent) near50 solder near50 mask near50 conductive near50 contact near50 pad	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/23 08:57
L24	947	228/179.1.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/23 09:22
L25	975	228/175.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/23 08:58
L26	1207	228/180.22.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/23 08:59
L27	3047	24 or 25 or 26	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/23 08:59
L28	1917	24 or 25 or 26	US-PGPUB; USPAT	OR	ON	2005/09/23 08:59

L29	3047	24 or 25 or 26	US-PGPU B; USPAT; USOCR; EPO; JPO; DERWEN T	OR	ON	2005/09/23 09:00
L32	9	29 and solder near50(mask or resist) and remov$3 and reflow and vias and (signal or power or ground) near50(plane or interconnect$3)	US-PGPU B; USPAT; USOCR; EPO; JPO; DERWEN T	OR	ON	2005/09/23 09:16
L33	15	24 and (solder near50 mask) and reflow	US-PGPU B; USPAT; USOCR; EPO; JPO; DERWEN T; IBM_TDB	OR	ON	2005/09/23 09:31
L34	214	29 and (solder near50 mask) and reflow and(ball or bump)	US-PGPU B; USPAT; USOCR; EPO; JPO; DERWEN T; IBM_TDB	OR	ON	2005/09/23 09:40
L35	15	("5471090" | "5663594" | "5859474" | "5895554" | "5917149" | "5951304"). PN. OR ("6078505"). URPN.	US-PGPU B; USPAT; USOCR	OR	ON	2005/09/23 11:02
L36	1	"20010013654"	US-PGPU B; USPAT; USOCR	OR	ON	2005/09/23 11:03

L41	1	36 and mask and ball and ground and power and signal	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/23 11:08
L44	4	("2001/0013654").URPN.	USPAT	OR	ON	2005/09/23 11:10
L45	47	("20010013654" | "20020008314" | "20020070443" | "20020158334" | "5055532" | "5105257" | "5327012" | "5346858" | "5353498" | "5355283" | "5422513" | "5497033" | "5503286" | "5523622" | "5527741" | "5608262" | "5701032" | "5703400" | "5707894" | "5745984" | "5798567" | "5844317" | "5864470" | "6014317" | "6049465" | "6060777" | "6084297" | "6084777" | "6130478" | "6153448" | "6154366" | "6162652" | "6222246" | "6239482" | "6242282" | "6249044" | "6255737" | "6271469" | "6284566" | "6287893" | "6291775" | "6333565" | "6388333" | "6388337" | "6396148" | "6590291" | "6621155").PN. OR ("6894399").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/09/23 11:11
L46	5	45 and mask and ball and power and signal and ground	US-PGPUB; USPAT; USOCR	OR	ON	2005/09/23 11:15
L47	4	45 and mask and reflow and ball and power and signal and ground	US-PGPUB; USPAT; USOCR	OR	ON	2005/09/23 11:15

L48	261	("4792646" | "5136366" | "5153385" | "5241133"). PN. OR ("5355283"). URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/09/23 11:40
L50	11	(("6555761") or ("6933449") or ("6884939") or ("6774310") or ("6486589") or ("6627822") or ("6730860") or ("6818155") or ("6803527") or ("6875367") or ("6461891")).PN.	US-PGPUB; USPAT; USOCR	OR	OFF	2005/09/23 11:47
L51	1	("20030218235").PN. OR ("6884939").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/09/23 11:49
L52	1	("20030218235").PN. OR ("6884939").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/09/23 12:33
L53	15	("4861941" | "5088007" | "5686699" | "5786630" | "5842877" | "5847936" | "5973929" | "6064113" | "6191475" | "6198635" | "6346679" | "6388890" | "6448639" | "6449169" | "6479758").PN. OR ("6730860").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/09/23 12:33
L54	65	("5191174" | "5400220" | "5450283" | "5535101" | "5598036" | "5615477"). PN. OR ("5847936"). URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/09/23 13:02
L55	98310	"361"/$	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/23 13:02

L56	59771	"174"/$	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/23 13:02
L57	137045	55 or 56	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/23 13:03
L60	403	57 and (solder near50 mask) and ((signal or ground or power) and alternat$3 or parallel) and form$3 and (capacitor or capacitance)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/23 13:09
L61	92	60 and reflow and contact near50 (pad or land)and heat$3 and remov$3	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/23 13:11
L62	15	("4861941" | "5088007" | "5686699" | "5786630" | "5842877" | "5847936" | "5973929" | "6064113" | "6191475" | "6198635" | "6346679" | "6388890" | "6448639" | "6449169" | "6479758").PN. OR ("6730860").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/09/23 15:32

L65	1952	62 or (solder near50 (mask or resist) near50 (remov$3 or clean$3 or dislodg$3)) and (reflow or heat$3)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/23 15:35
L66	251	65 and (signal or power or ground) near50 (via or bar or plane)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/23 15:39
L67	22	("4573261" | "4668533" | "4748453" | "4767489" | "4824010" | "4963882" | "4999646" | "5207115" | "5239312" | "5270368" | "5356658" | "5560534" | "5587730" | "5590455" | "5637426" | "5640183" | "5790150" | "5793392" | "5984455" | "6000124" | "6076910" | "6439681"). PN. OR ("6754551"). URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/09/23 16:13
L68	6	("4854040").URPN.	USPAT	OR	ON	2005/09/23 16:26
S23	663	228/56.3.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/22 13:47

S24	103	228/111.5.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/21 16:16
S25	1207	228/180.22.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/21 16:16
S26	1926	S23 or S24 or S25	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/21 16:17
S27	48	S26 and solder near50(bump or ball) near50 mask near50 remov$3 naer50 permanent near50 (contact near20 pad) near50 exposed near50 plurality near20 (capacitor or land) near50 solidify$3 near50 melt$3	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/21 16:49
S28	4	("5034345" | "5376584" | "5656863" | "5660321"). PN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/09/21 16:26

S29	1	S26 and vias and (contact near20 pad) and (permanent or remov$3) near20 (solder near20 mask) and (power or ground) near20 plane near20 separat$3 near50 layers	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/21 16:54
S30	9	S26 and vias and (contact near20 pad) and (permanent or remov$3) and (solder near20 mask) and (power or ground) and plane and separat$3 and layers	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/21 16:54
S31	83	("3621564" | "3645392" | "3719981" | "4119480" | "4311267" | "4722470" | "4752027" | "4825034" | "4914814" | "5024372" | "5057969" | "5118027" | "5133495" | "5145104" | "5196726" | "5203075" | "5219117" | "5261155" | "5261593" | "5275970" | "5341564" | "5346118" | "5388327" | "5468681" | "5492266" | "5539333" | "5542601" | "5545465" | "5564617" | "5586715" | "5597469" | "5607099" | "5623506" | "5643831" | "5658827").PN. OR ("5872051").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/09/21 17:00
S32	79	("3214827" | "3379937" | "3380155" | "4545610" | "4565314" | "4818728" | "4836435" | "4998665" | "5006920" | "5007163" | "5075965" | "5214308" | "5250469").PN. OR ("5341564").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/09/21 17:25
S33	18	("5341564" | "5952718"). PN. OR ("6190940"). URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/09/21 17:34

S34	26	package and substrate and printed and circuit and (power or ground or signal) and (vias or plane or pad) and solder and connection and mask and transmit$3 and communicat$3 and conduct$3 and path and heat$3 and cool$3 and (solidify or solidification or solidified) and current	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/22 14:01
S35	9	package and substrate and printed and circuit and (power or ground or signal) near50 (vias or plane or pad) and (solder near50 mask) and transmit$3 and (conduct$3 near50 path) and heat$3 and cool$3 and (solidify or solidification or solidified)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/22 14:03
S36	54	("2734154" | "4034468" | "4034469" | "4254431" | "4299715" | "4323914" | "4398975" | "4435611" | "4466483" | "4473113" | "4607277" | "4806111" | "4915167" | "4966142" | "5011787" | "5031308" | "5037312" | "5056706" | "5071787" | "5074947" | "5086558" | "5097387" | "5131582" | "5148141" | "5148265" | "5148266" | "5164566" | "5170930" | "5196371" | "5198189" | "5223747" | "5237130" | "5323294" | "5325265" | "5328087" | "5445308" | "5455390" | "5459352" | "5542602" | "5553769" | "5557501" | "5561590" | "5572404" | "5651179" | "5658831" | "5688721" | "5720100" | "5808874" | "5819406" | "5920125" | "5975408" | "6000127"). PN. OR ("6202298"). URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/09/22 14:10

S37	31	("4604644" | "4999699" | "5007163" | "5170930" | "5391514").PN. OR ("5553769").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/09/22 14:18
S38	10	("20020109227" | "4893172" | "5553769" | "5796590" | "6133978" | "6204163" | "6208027" | "6407451" | "6495926"). PN. OR ("6664625"). URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/09/22 14:19
S39	73	("4142286" | "5051339" | "5164818" | "5189507" | "5255431" | "5337219" | "5403671" | "5435482" | "5442852" | "5453581" | "5463191" | "5477933"). PN. OR ("5796590"). URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/09/22 14:34
S40	161	S36 or S37 or S38 or S39	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/22 14:34
S41	19	S40 and (signal or groung or power) near50 (vias or (contact near10 pad))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/22 14:37
S42	14	("3872583" | "4646435" | "5222014" | "5237743" | "5473510" | "5477933" | "5541450" | "5553769"). PN. OR ("5808875"). URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/09/22 14:38

S43	75	("4092697" | "4141135" | "4156458" | "4161701" | "4180414" | "4295183" | "4322778" | "4349862" | "4498530" | "4612601" | "4617730" | "4639829" | "4652977" | "4698663" | "4717591" | "4729060" | "4740866" | "4758926" | "4926241" | "4942076"). PN. OR ("5325265"). URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/09/22 15:58
S44	396	(mount$3 or connect$3) and integrated and circuit and package and substrate and (permanent or remov$3) with solder with mask	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/22 17:12
S45	58	S44 and (signal or ground or power) near50 vias	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/22 16:09
S46	58	S44 and (signal or ground or power) near50 via	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/22 16:09

S47	19	("2427144" | "4048438" | "4177519" | "4383363" | "4949155" | "5243142" | "5535101" | "5600103" | "5736681" | "5737833" | "5758413" | "5798563" | "5870289" | "5909010" | "5979044" | "6010769" | "6052287" | "6075710"). PN. OR ("6915566"). URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/09/22 16:20
S48	91	("5068714" | "5406459" | "5407864" | "5611884"). PN. OR ("5870289"). URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/09/22 16:26
S49	45	("3372310" | "3671812" | "3991347" | "4107760" | "4122508" | "4291364" | "4315300" | "4339628" | "4375290" | "4423468" | "4549200" | "4580193" | "4619316" | "4674004" | "4730232" | "4739444" | "4771366" | "4782381" | "4783695" | "4830264" | "4831433" | "4835344" | "4838475" | "4841355" | "4868634" | "4956746" | "5023754" | "5027505" | "5057971" | "5101322"). PN. OR ("5208729"). URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/09/22 17:09
S50	760	integrated with circuit with package with (power or ground or signal)near50(vias or plane or bar)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/22 17:26

S51	25	S50 with solder near20(ball or mask)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/22 17:26
S52	1747	integrated with circuit with package with (power or ground or signal)near50(vias or connect$3 or bar)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/22 17:26
S53	40	S52 with solder near20(ball or mask)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/22 17:26
S54	4	("2001/0013654").URPN.	USPAT	OR	ON	2005/09/22 17:27